WIRE BONDING APPARATUS AND METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE

ABSTRACT

A wire bonding apparatus includes: a bonding tool 40 into and through a wire 42 passes; a control unit 80 that performs a movement process of the bonding tool 40 for cutting the wire 42 after forming a wire loop 90 between first and second bonding points of a bonding target 100; and a monitoring unit 70 that supplies a predetermined electric signal between the wire 42 through the bonding tool 40 and the bonding target 100, and monitors whether the wire 42 is cut or not based on an output of the supplied electric signal. The control unit 80 continues the movement process of the bonding tool 40 while the wire 42 is determined not to be cut, and stops the movement process of the bonding tool 40 when the wire 42 is determined to be cut, based on a monitoring result from the monitoring unit 70. This can shorten the operation time of the wire bonding, and improve the process efficiency of the wire bonding.

Fig. 4A – 4B